

ABSTRACT OF THE DISCLOSURE

A system and method for distributing power to an integrated circuit. In one embodiment, a power laminate may be mounted to a printed circuit board (PCB). The integrated circuit for which power is to be distributed may be electrically coupled to the PCB. The power laminate may include one or more power planes and one or more reference (i.e. ground) planes, with each pair of power/reference planes separated by a dielectric layer. The power laminate may also include a connector or other means for receiving power from an external power source. The power laminate may be electrically coupled to the integrated circuit, thereby enabling it to provide power to the integrated circuit. The power laminate may also include a voltage regulator circuit, and a plurality of decoupling capacitors.

15

20

25